



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL32A226KOJNNNE

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22 µF, 16V, ±10%, X5R, 1210

A. Samsung Part Number

<u>CL</u> <u>32</u> <u>A</u> <u>226</u> <u>K</u> <u>O</u> <u>J</u> <u>N</u> <u>N</u> <u>N</u> <u>E</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor								
2	Size	1210 (inch c	ode)	L: 3.2	± 0.3	mm	W:	2.5	± 0.2	mm
3	Dielectric	X5R		8	Inner e	lectrode		Ni		
4	Capacitance	22 μF			Termin	ation		Cu		
(5)	Capacitance	±10 %			Plating			Sn 10	00%	(Pb Free)
	tolerance			9	Produc	t		Norm	al	
6	Rated Voltage	16 V		Special		Reserved for futur		future use		
7	Thickness	2.5 ± 0.2	mm	11)	Packag	jing		Embo	ssed T	ype, 7" reel

B. Samsung Reliability Test and Judgement condition

	Performance	Test condition						
Capacitance	Within specified tolerance	120Hz ±20% 0.5±0.1Vrms						
Tan δ (DF)	0.1 max.							
Insulation	10,000Mohm or 100Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.						
Resistance	Whichever is Smaller							
Appearance	No abnormal exterior appearance	Microscope (×10)						
Withstanding	No dielectric breakdown or	250% of the rated voltage						
Voltage	mechanical breakdown							
Temperature	X5R							
characteristics	(From -55℃ to 85℃, Capacitance change should be within ±15%)							
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.						
of Termination	terminal electrode							
Bending Strength	Capacitance change: within ±12.5%	Bending to the limit (1mm)						
		with 1.0mm/sec.						
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder						
	is to be soldered newly	245±5℃, 3±0.3sec.						
		(preheating : 80~120 ℃ for 10~30sec.)						
Resistance to	Capacitance change: within ±7.5%	Solder pot : 270±5°C, 10±1sec.						
Soldering heat	Tan δ , IR : initial spec.	001d01 pot: 27020 0, 1021000.						

	Performance	Test condition					
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm					
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)					
		2hours × 3 direction (x, y, z)					
Moisture	Capacitance change: within ±12.5%	With rated voltage					
Resistance	Tan δ: 0.125 max	40±2℃, 90~95%RH, 500+12/-0hrs					
	IR: 12.5M\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\						
High Temperature	Capacitance change: within ±12.5%	With 150% of the rated voltage					
Resistance	Tan δ : 0.125 max	Max. operating temperature					
	IR : 25MΩ·μF or Over						
		1000+48/-0hrs					
Temperature	Capacitance change: within ±7.5%	1 cycle condition					
Cycling	Tan δ, IR : initial spec.	Min. operating temperature → 25°C					
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!\!$					
		5 cycle test					

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C , 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.